Title (en)

PROCESS METHOD USING ORGANIC SILICONE RESIN PHOTOCONVERTER TO BOND-PACKAGE LED BY TANDEM ROLLING

Title (de)

PROZESSVERFAHREN MIT VERWENDUNG EINES PHOTOKONVERTERS FÜR ORGANISCHES SILIKONHARZ ZUR BOND-VERPACKUNG EINER LED DURCH TANDEMWALZEN

Title (fr)

PROCÉDÉ DE TRAITEMENT UTILISANT UN PHOTOCONVERTISSEUR EN RÉSINE DE SILICONE ORGANIQUE POUR COLLER-ENCAPSULER UNE DEL PAR CYLINDRAGE EN TANDEM

Publication

EP 3340320 A4 20180801 (EN)

Application

EP 15901631 A 20151218

Priority

- CN 201510509581 A 20150818
- CN 2015097906 W 20151218

Abstract (en)

[origin: EP3340320A1] Provided is a process method for bond-packaging an LED using an organic silicone resin photoconverter by tandem rolling, including the following continuous process flow: preparation of a semi-cured photoconversion sheet, pseudo-curing of the semi-cured photoconversion sheet, preparation of a flip chip LED array sheet, forming of LED package elements by dual-roller roll-bonding, curing of the LED package elements, and cutting of the LED package elements. The present invention has a significant advantage of bond-packaging an LED by using a continuous rolling process, and can satisfy a condition requirement of bond-packaging an LED using an organic silicone resin photoconverter, thereby improving the production efficiency and yield of LED packages in industrialized batch production.

IPC 8 full level

H01L 33/50 (2010.01); **H01L 25/075** (2006.01); **H01L 33/48** (2010.01)

CPC (source: CN EP KR US)

H01L 25/075 (2013.01 - US); **H01L 25/0753** (2013.01 - CN); **H01L 27/153** (2013.01 - US); **H01L 33/005** (2013.01 - KR US); **H01L 33/48** (2013.01 - CN US); **H01L 33/483** (2013.01 - US); **H01L 33/50** (2013.01 - US); **H01L 33/501** (2013.01 - EP US); **H01L 33/505** (2013.01 - CN KR); **H01L 33/52** (2013.01 - KR US); **H01L 33/56** (2013.01 - US); B32B 37/0053 (2013.01 - EP); B32B 37/06 (2013.01 - EP); B32B 37/08 (2013.01 - EP); B32B 38/10 (2013.01 - EP); B32B 2037/1253 (2013.01 - EP); B32B 2309/02 (2013.01 - EP); B32B 2457/00 (2013.01 - EP); H01L 2933/0033 (2013.01 - CN EP KR); H01L 2933/0041 (2013.01 - CN EP); H01L 2933/005 (2013.01 - KR)

Citation (search report)

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- [A] EP 2634805 A1 20130904 - NITTO DENKO CORP [JP]
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Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

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BA ME

DOCDB simple family (publication)

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